



**RevB:**

- 1) lowered current sense R1
- 2) tuned loop
- 3) VENABLE: TP11 sw / TP8 rt / TP7 br

**ASSEMBLY:**

- 1) built on PCB PM2091RevA
- 2) D1 in SMB will not meet SMA pattern
- 3) L2 OPEN
- 4) L1, 1210 meets DR127 pattern
- 5) C6 on 0805 pattern, R1 on 0805 pattern

**NOTES:**

- 1) R9 for test purposes only

Orderable:	Designed for:	Mod. Date: 2/19/2016
TID #:	Project Title: Basic Inverting Buck Boost	
Number: PMP7207	Rev: B	Sheet Title: TPS40200, -12V inv. buckboost
Rev: Version control disabled	Assembly Variant: No Variations	Sheet: 1 of 1
Drawn By:	File: PMP7207RevB_SchDoc	Size: B
Engineer: B.Geck	Contact: TechSupport	

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